

SeerSense™ DS80 Module

Edge computing VSLAM, AI, and CV engines

Package



SeerSense™ DS80



SDK



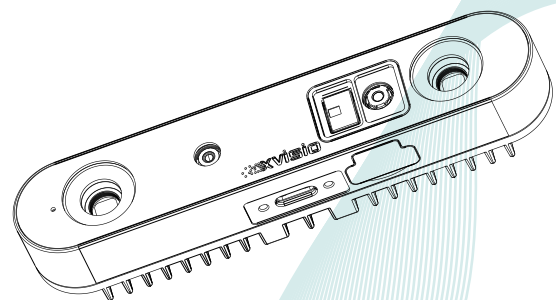
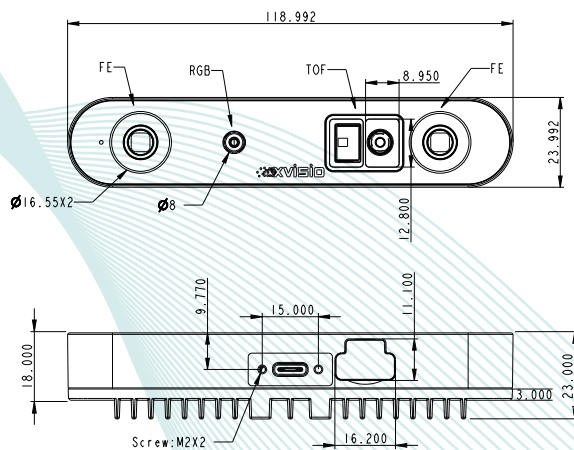
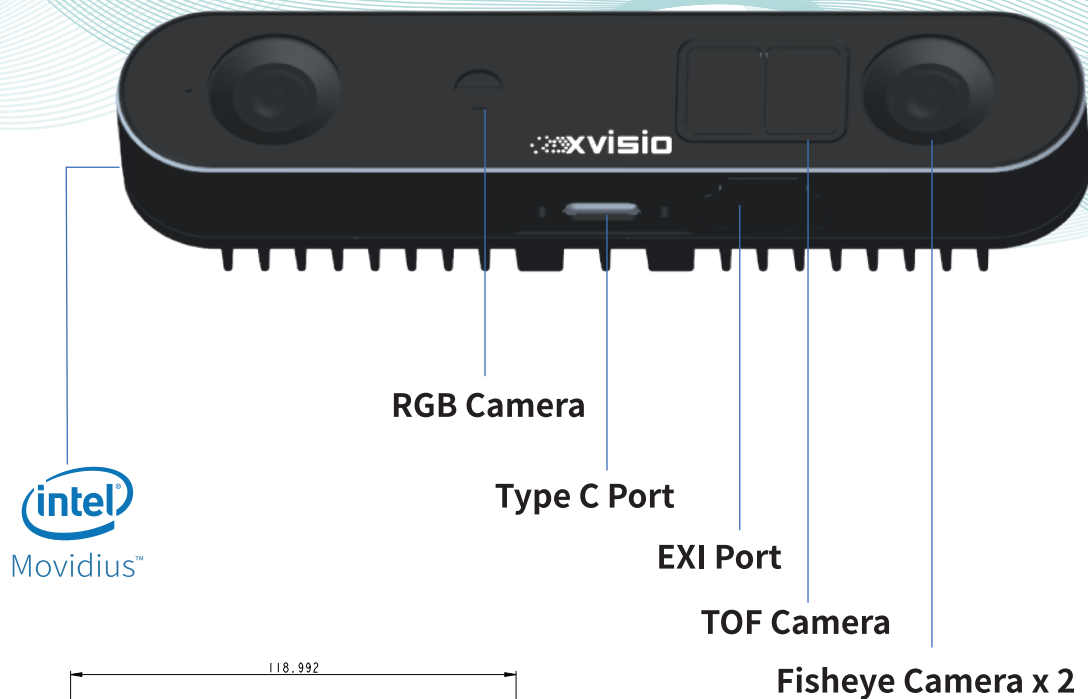
Tool Chain

System Spec

Item	Spec	Remark
Processor	Myriad X	Intel Movidius VPU
Cameras		
-Stereo	1280x800/640x400,60fps DFOV150°/ HFOV130°/VFOV74°	Mono, Global shutter 80mm baseline
-RGB	8MP (4192x3104), 30fps DFOV79.9°/HFOV68°/VFOV53°	Photo: 8.2MP/13MP (MAX) Video: VGA/720P/1080P @ 30fps
-TOF	640x480/320x240, 30fps DFOV78°/ HFOV64°/ VFOV50°	0.5-5m =<1% depth error 940nm, Class 1 laser eye safety compliant
IMU	9 Axis	1000Hz fusion for VSLAM
CNN Engine	Dual engine	Parallel processing
Stereo Depth Engine	VGA/720P SGBM (Semi-Global Block Match)	50/60fps, 6.5 meter
6DoF SLAM Engine	500-1000Hz mm accuracy	On board processing Multiple working mode
Power Consumption	Avg 2.8W	
Supply Voltage	5V 3A	
Port	USB Type C	Camera Stream, Depth, AI image, 6DoF Output
	Debug Port	UART, Sync Pin
Weight Size	93g 119Lx23Dx24H	LxDxH (mm)
SDK	VIO, CSLAM, 3D reconstruction, Depth/Point Cloud (SGBM/TOF) Object detection, Gesture, Plane detection, RGBD camera	
Tool Chain	Open VINO, Open CV, Xvsdk-viewer Demo Tool	

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Dimensions (mm)

Key Benefits

- One-stop solution for VSLAM, depth, vision AI, CV edge computing
- Multiple OS support for wide range of deployment
- Both passive (SGBM) and active (TOF) depth engine on one device
- Edge computing to offload host resource loading
- Feature-rich SDKs and tool kit for fast development
- Compact, portable, and low power consumption

CE CB FC FMA RoHS	
Laser module class	Class 1 laser product
Standard	IEC 60825-1:2014
Laser module Vf(V) Max	2.3
Optical power(W) Max	2.6
Wavelength(nm)	940

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